

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>0</b>	<b>microcircuit and package and stacking and pretested adj circuit</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 10:51</b>
<b>2</b>	<b>0</b>	<b>package and stacking and pretested adj circuit</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 10:52</b>
<b>3</b>	<b>0</b>	<b>package and pretested adj circuit</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 10:52</b>
<b>4</b>	<b>2</b>	<b>pretested adj circuit</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 10:54</b>
<b>5</b>	<b>5</b>	<b>pretested and microcircuit</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 10:57</b>
<b>6</b>	<b>19</b>	<b>pre-tested and circuit and 29/\$.ccis.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 10:58</b>

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>43</b>	<b>circuit adj board and encapsulated and grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:22</b>
<b>2</b>	<b>34</b>	<b>IC and encapsulated and grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:35</b>
<b>3</b>	<b>0</b>	<b>20020100600.URPN.</b>	<b>USPAT</b>	<b>2002/08/06 08:26</b>
<b>4</b>	<b>1</b>	<b>microcircuit and encapsulated and grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:35</b>
<b>5</b>	<b>66</b>	<b>circuit and encapsulated and grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:39</b>
<b>6</b>	<b>5</b>	<b>("3370203"   "3577037"   "4151543"   "4363076"   "4398235").PN.</b>	<b>USPAT</b>	<b>2002/08/06 08:37</b>
<b>9</b>	<b>9</b>	<b>circuit and encapsulated and grinding and polishing and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:40</b>
<b>10</b>	<b>8</b>	<b>BGA and encapsulated and grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:42</b>
<b>11</b>	<b>3</b>	<b>("5304534"   "5373627"   "5847445").PN.</b>	<b>USPAT</b>	<b>2002/08/06 08:41</b>
<b>12</b>	<b>13</b>	<b>encapsulated and grinding and stacking and 29/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:44</b>
<b>13</b>	<b>1</b>	<b>chip and encapsulated near grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:45</b>
<b>14</b>	<b>1</b>	<b>encapsulated near grinding and stacking</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2002/08/06 08:47</b>

15	0	20010055856.URPN.	USPAT	2002/08/06 08:46
16	7	grinding and stacking and 438/460.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:55
17	4	grinding and stacking and 438/462.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:55
18	2	grinding and stacking and 438/465.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 08:57
19	1	"5646067".PN.	USPAT	2002/08/06 08:56
20	0	20010055856.URPN.	USPAT	2002/08/06 08:57
21	178	grinding and stacking and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 09:25
22	6	("4750090"   "5657537"   "5699234"   "5739578"   "5844168"   "6290540").PN.	USPAT	2002/08/06 08:59
23	14	("4237522"   "4254446"   "4783695"   "4835704"   "4894115"   "4933042"   "5019946"   "5111278"   "5161093"   "5279029"   "5285571"   "5347928"   "5466634"   "5502667").PN.	USPAT	2002/08/06 09:01
24	40	("2907926"   "3029495"   "3065384"   "3070729"   "3139559"   "3152288"   "3370203"   "3746934"   "3748479"   "4520427"   "4525921"   "4551629"   "4612083"   "4638348"   "4646128"   "4706166"   "4727410"   "4764846"   "4801992"   "4818728"   "4833568"   "4862249"   "4868712"   "4879258"   "4894706"   "4901136"   "4902641"   "4926241"   "4956746"   "4983533"   "5016138"   "5019943"   "5019946"   "5051865"   "5064771"   "5071792"   "5091331"   "5162254"   "5266833"   "5347428").PN.	USPAT	2002/08/06 09:06
25	9	grinding and stacking and (albert et al).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 09:27

-	2	5086018.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 14:59
-	2	6342398.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:45
-	2	6060373.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:45
-	3	5454160.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:45
-	7	microcircuit and package and stacking and 29/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 13:59
-	71	5086018.URPN.	USPAT	2002/08/05 14:53
-	36	("4862245"   "4937656"   "4949161"   "5086018"   "5147815"   "5218168"   "5234866"   "5250840"   "5256598"   "5303120"   "5327009"   "5331200"   "5334873"   "5357139"   "5360992"   "5365113"   "5381036"   "5384488"   "5434106"   "5438478"   "5508565"   "5521426"   "5523617"   "5528075"   "5530292"   "5563443"   "5585667"   "5585668"   "5612259"   "5637915"   "5696665"   "5751057"   "5780925"   "5804870"   "5811875"   "6066515").PN.	USPAT	2002/08/05 14:56

-	84	("3246386"   "3290559"   "3313986"   "3377516"   "3403300"   "3515949"   "3535595"   "3614541"   "3671812"   "3746934"   "3949274"   "3959579"   "4017963"   "4116518"   "4116519"   "4288808"   "4288841"   "4364620"   "4371912"   "4379259"   "4394712"   "4398235"   "4571663"   "4574331"   "4631573"   "4638348"   "4638406"   "4642735"   "4688864"   "4696525"   "4698663"   "4706166"   "4761681"   "4770640"   "4821007"   "4841355"   "4868712"   "4884237"   "4924352"   "4953005"   "4956694"   "4996583"   "4996587"   "5016138"   "5025307"   "5031072"   "5041395"   "5043794"   "5058265"   "5086018"   "5107328"   "5128831"   "5140745"   "5155068"   "5198888"   "5222014"   "5231304"   "5239447"   "5241454"   "5281852"   "5311401"   "5313096"   "5343075"   "5343366"   "5369058"   "5373189"   "5384689"   "5397916"   "5420751"   "5426566"   "5446313"   "5479318"   "5481133"   "5493476"   "5499160"   "5514907"   "5552963"   "5561591"   "5566051"   "5586009"   "5605592"   "5612570"   "5615475"   "5723903").PN.	USPAT	2002/08/05 14:57
-	14	("3746934"   "4398235"   "4521828"   "4763188"   "4796078"   "4884237"   "4953060"   "4956694"   "5151559"   "5221642"   "5270492"   "5279029"   "5367766"   "5394010").PN.	USPAT	2002/08/05 14:58
-	4	29/841.ccls. and IC and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:02
-	0	29/841.ccls. and "PEM" and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:02
-	0	29/841.ccls. and "PEM"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:02
-	0	29/841.ccls. and "Plastic encapsulant microcircuit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:03

-	0	"Plastic encapsulant microcircuit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:03
-	0	"plastic encapsulant microcircuit"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:04
-	0	plastic same encapsulant near microcircuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:04
-	14	plastic same encapsulant near circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:05
-	0	encapsulant near circuit and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:06
-	263	encapsulant and circuit and stacking	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:06
-	31	encapsulant and circuit and stacking and 174/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:07
-	13	encapsulant and circuit and stacking and 439/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:08
-	10	encapsulant and circuit and stacking and 228/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:08
-	134	encapsulant and circuit and stacking and 257/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/05 15:09